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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	20000
Number of Logic Elements/Cells	80000
Total RAM Bits	5816320
Number of I/O	904
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1704-BCBGA, FCBGA
Supplier Device Package	1704-CFCBGA (42.5x42.5)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga80ep1-6fcn1704c

Table 2-5. sysMEM Block Configurations

Memory Mode	Configurations
Single Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
True Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18
Pseudo Dual Port	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36
FIFO	16,384 x 1 8,192 x 2 4,096 x 4 2,048 x 9 1,024 x 18 512 x 36

Bus Size Matching

All of the multi-port memory modes support different widths on each of the ports. The RAM bits are mapped LSB word 0 to MSB word 0, LSB word 1 to MSB word 1 and so on. Although the word size and number of words for each port varies, this mapping scheme applies to each port.

RAM Initialization and ROM Operation

If desired, the contents of the RAM can be pre-loaded during device configuration. By preloading the RAM block during the chip configuration cycle and disabling the write controls, the sysMEM block can also be utilized as a ROM.

Single, Dual and Pseudo-Dual Port Modes

In all the sysMEM RAM modes the input data and address for the ports are registered at the input of the memory array. The output data of the memory is optionally registered at the output. A clock is required even in asynchronous read mode.

The EBR memory supports two forms of write behavior for dual port operation:

1. **Normal** — data on the output appears only during a read cycle. During a write cycle, the data (at the current address) does not appear on the output.

2. **Write Through** — a copy of the input data appears at the output of the same port.

FIFO Configuration

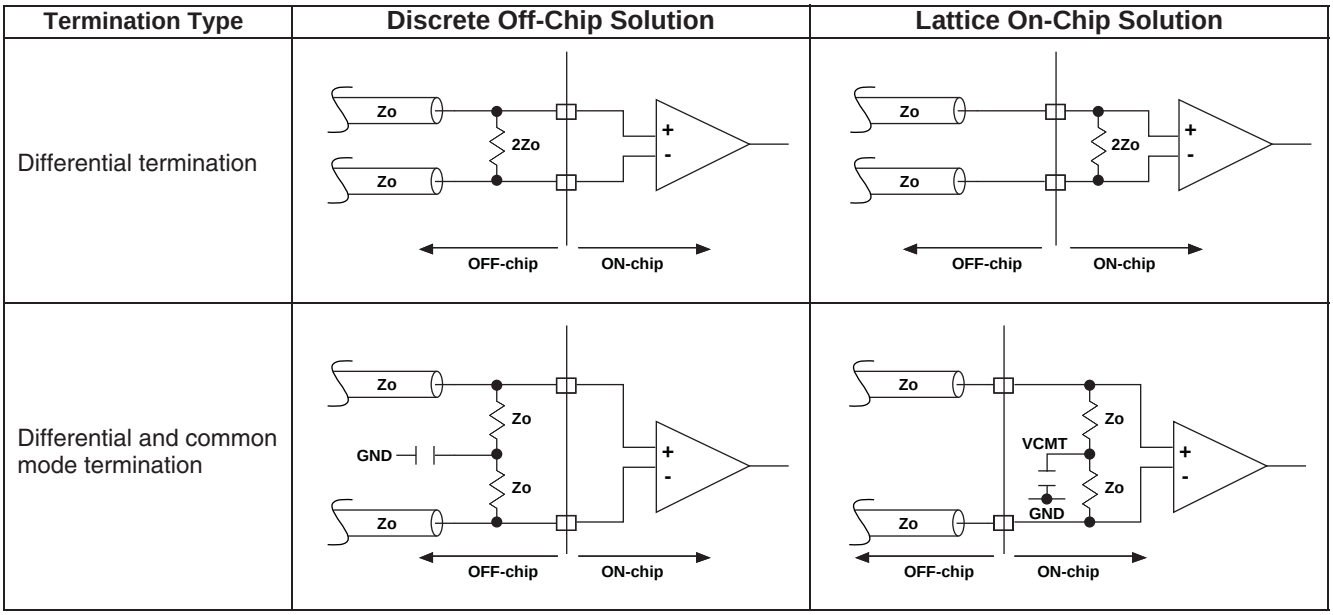
The FIFO has a write port with Data-in, WCE, WE and WCLK signals. There is a separate read port with Data-out, RCE, RE and RCLK signals. The FIFO internally generates Almost Full, Full, Almost Empty, and Empty Flags. The Full and Almost Full flags are registered with WCLK. The Empty and Almost Empty flags are registered with RCLK.

Differential Input Termination

The LatticeSC device allows two types of differential termination. The first is a single resistor across the differential inputs. The second is a center-tapped system where each input is terminated to the on-chip termination bus V_{CMT}. The V_{CMT} bus is DC-coupled through an internal capacitor to ground.

Figure 2-29 shows the differential termination schemes and Table 2-9 shows the nominal values of the termination resistors.

Figure 2-29. Differential Termination Scheme



Calibration

There are two calibration sources that are associated with the termination scheme used in the LatticeSC devices:

- DIFFR – This pin occurs in each bank that supports differential drivers and must be connected through a 1K+/-1% resistor to ground if differential outputs are used. Note that differential drivers are not supported in banks 1, 4 and 5.
- XRES – There is one of these pins per device. It is used for several functions including calibrating on-chip termination. This pin should always be connected through a 1K+/-1% resistor to ground.

The LatticeSC devices support two modes of calibration:

- Continuous – In this mode the SC devices continually calibrate the termination resistances. Calibration happens several times a second. Using this mode ensures that termination resistances remain calibrated as the silicon junction temperature changes.
- User Request – In this mode the calibration circuit operates continuously. However, the termination resistor values are only updated on the assertion of the calibration_update signal available to the core logic.

For more information on calibration, refer to the details of additional technical documentation at the end of this data sheet.

Hot Socketing

The LatticeSC devices have been carefully designed to ensure predictable behavior during power-up and power-down. To ensure proper power sequencing, care must be taken during power-up and power-down as described below. During power-up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled to within specified limits,

Power Supply Ramp Rates

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
t_{RAMP}	Power supply ramp rates for all power supplies	Over process, voltage, temperature	3.45	—	—	mV/µs
			—	—	75	ms

1. See the Power-up and Power-Down requirements section for more details on power sequencing.
2. From 0.5V to minimum operating voltage.

Hot Socketing Specifications[1]

Symbol	Parameter	Condition	Min.	Typ.	Max	Units
I_{DK}	Programmable and dedicated Input or I/O leakage current[2, 3, 4, 5, 6]	0 <= V_{IN} <= V_{IH} (MAX)	—	—	±1500	µA
I_{HDIN}	SERDES average input current when device powered down and inputs driven[7]		—	—	4	mA

1. See Hot Socket power up/down information in Chapter 2 of this document.
2. Assumes monotonic rise/fall rates for all power supplies.
3. Sensitive to power supply sequencing as described in hot socketing section.
4. Assumes power supplies are between 0 and maximum recommended operations conditions.
5. IDK is additive to I_{PU}, I_{PD} or I_{BH}.
6. Represents DC conditions. For the first 20ns after hot insertion, current specification is 8 mA.
7. Assumes that the device is powered down with all supplies grounded, both P and N inputs driven by a CML driver with maximum allowed VDDOB of 1.575V, 8b/10b data and internal AC coupling.

DC Electrical Characteristics[5]

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.[3]	Typ.	Max.	Units
I_{IL}, I_{IH}[1]	Input or I/O Low leakage	0 ≤ V_{IN} ≤ V_{IH} (MAX)	—	—	10	µA
I_{PU}	I/O Active Pull-up Current	0 ≤ V_{IN} ≤ 0.7 V_{CCIO}	-30	—	-210	µA
I_{PD}	I/O Active Pull-down Current	V_{IL} (MAX) ≤ V_{IN} ≤ V_{IH} (MAX)	30	—	210	µA
I_{BHLS}	Bus Hold Low Sustaining Current	V_{IN} = V_{IL} (MAX)	30	—	—	µA
I_{BHHS}	Bus Hold High Sustaining Current	V_{IN} = 0.7V_{CCIO}	-30	—	—	µA
I_{BHLO}	Bus Hold Low Overdrive Current	0 ≤ V_{IN} ≤ V_{IH} (MAX)	—	—	210	µA
I_{BHLH}	Bus Hold High Overdrive Current	0 ≤ V_{IN} ≤ V_{IH} (MAX)	—	—	-210	µA
I_{CL}	PCI Low Clamp Current	-3 < V_{IN} ≤ -1	-25 + (V_{IN} + 1)/0.015	—	—	mA
I_{CH}	PCI High Clamp Current	V_{CC} + 4 > V_{IN} ≥ V_{CC} + 1	25 + (V_{IN} - V_{CC} -1)/ 0.015	—	—	mA
V_{BHT}	Bus Hold trip Points	0 ≤ V_{IN} ≤ V_{IH} (MAX)	V_{IL} (MAX)	—	V_{IH} (MIN)	V
C1	I/O Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	8	—	pf
C3[2]	Dedicated Input Capacitance[2]	V_{CCIO} = 3.3V, 2.5V, 1.8V, 1.5V, 1.2V, V_{CC} = 1.2V, V_{CCIP2} = 1.2V, V_{CCAUX} = 2.5, V_{IO} = 0 to V_{IH} (MAX)	—	6	—	pf

1. Input or I/O leakage current is measured with the pin configured as an input or as an I/O with the output driver tri-stated. It is not measured with the output driver active. Bus maintenance circuits are disabled.
2. T_A 25°C, f = 1.0MHz
3. I_{PU}, I_{PD}, I_{BHLS} and I_{BHHS} have minimum values of 15 or -15µA if V_{CCIO} is set to 1.2V nominal.
4. This table does not apply to SERDES pins.
5. For programmable I/Os.

Initialization and Standby Supply Current

The table below indicates initialization and standby supply current while operating at 85°C junction temperature (T_J), which is the high end of the commercial temperature range, and 105°C, which is the high end of the industrial temperature range. This data assumes all outputs are tri-stated and all inputs are configured as LVCMOS and held at V_{CCIO} or GND. The remaining SERDES supply current for V_{DDIB} and V_{DDOB} is detailed in the SERDES section of this data sheet. For power at your design temperature, it is recommended to use the Power Calculator tool which is accessible in ispLEVER or can be used as a standalone tool. For more information on supply current, see the reference to additional technical documentation available at the end of this data sheet.

Over Recommended Operating Conditions

Symbol	Condition	Parameter	Device	25°C Typ.[1]	85°C Max.[2]		105°C Max.[2]	Units
				All	-5, -6	-7	-5, -6	
I_{CC}	(VCC = 1.2V +/- 5%)	Core Operating Power Supply Current	LFSC/M15	65	449	678	755	mA
			LFSC/M25	113	798	1255	1343	mA
			LFSC/M40	159	1178	2006	1981	mA
			LFSC/M80	276	2122	3827	3569	mA
			LFSC/M115	454	3376	—	5679	mA
	(VCC = 1.0V +/- 5%)	Core Operating Power Supply Current	LFSC/M15	45	312	471	524	mA
			LFSC/M25	79	554	872	933	mA
			LFSC/M40	110	818	1393	1375	mA
			LFSC/M80	191	1473	2658	2478	mA
			LFSC/M115	315	2344	—	3943	mA
I_{CC12}		1.2V Power Supply Current for Configuration Logic, FPGA PLL, SERDES PLL and SERDES Analog Supplies	LFSC/M15	23	39	59	35	mA
			LFSC/M25	25	50	78	56	mA
			LFSC/M40	31	78	133	89	mA
			LFSC/M80	50	108	195	123	mA
			LFSC/M115	65	131	—	154	mA
I_{CCAUX}		Auxiliary Operating Power Supply Current	LFSC/M15	7	12	19	14	mA
			LFSC/M25	9	16	25	18	mA
			LFSC/M40	12	23	39	25	mA
			LFSC/M80	13	25	45	23	mA
			LFSC/M115	16	27	—	26	mA
I_{CCIO} and I_{CCJ}		Bank Power Supply Current (per bank)	LFSC/M15	0.1	0.2	0.3	0.2	mA
			LFSC/M25	0.3	0.6	1.0	0.7	mA
			LFSC/M40	0.4	0.9	1.5	1.0	mA
			LFSC/M80	0.5	1.1	2.1	1.3	mA
			LFSC/M115	0.7	1.5	—	1.8	mA

1. I_{CC} is specified at T_J = 25°C and typical V_{CC}.
2. I_{CC} is specified at the respective commercial and industrial maximum T_J and V_{CC} limits.

Switching Characteristics

All devices are 100% functionally tested. Listed below are representative values of internal and external timing parameters. For more specific, more precise, and worst-case guaranteed data at a particular temperature and voltage, use the values reported by the static timing analyzer in the ispLEVER design tool from Lattice and back-annotate to the simulation net list.

LatticeSC/M Family Timing Adders (Continued)

Over Recommended Operating Conditions at VCC = 1.2V +/- 5%

Buffer Type	Description	-7		-6		-5		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
GTLPLUS15	GTLPLUS15	-0.013	-0.017	0.012	0.004	0.037	0.024	ns
GTL12	GTL12	-0.063	-0.071	-0.007	-0.048	0.056	-0.032	ns
Output Adjusters								
LVDS	LVDS	0.708	0.854	0.856	1.021	1.005	1.189	ns
RSDS	RSDS	0.708	0.854	0.856	1.021	1.005	1.189	ns
BLVDS25	BLVDS	-0.129	0.05	-0.136	0.069	-0.136	0.083	ns
MLVDS25	MLVDS	-0.059	0.059	-0.057	0.096	-0.054	0.133	ns
LVPECL33	LVPECL	-0.334	-0.181	-0.325	-1.389	-0.315	-2.598	ns
HSTL18_I	HSTL_18 class I	0.132	0.209	0.153	0.24	0.175	0.272	ns
HSTL18_II	HSTL_18 class II	0.24	0.176	0.268	0.255	0.298	0.333	ns
HSTL18D_I	Differential HSTL 18 class I	0.132	0.209	0.153	0.24	0.175	0.272	ns
HSTL18D_II	Differential HSTL 18 class II	0.24	0.176	0.268	0.255	0.298	0.333	ns
HSTL15_I	HSTL_15 class I	0.096	0.172	0.112	0.198	0.129	0.224	ns
HSTL15_II	HSTL_15 class II	0.208	0.131	0.233	0.203	0.259	0.275	ns
HSTL15D_I	Differential HSTL 15 class I	0.096	0.172	0.112	0.198	0.129	0.224	ns
HSTL15D_II	Differential HSTL 15 class II	0.208	0.131	0.233	0.203	0.259	0.275	ns
SSTL33_I	SSTL_3 class I	0.133	0.177	0.11	0.166	0.088	0.154	ns
SSTL33_II	SSTL_3 class II	0.173	0.247	0.164	0.253	0.156	0.258	ns
SSTL33D_I	Differential SSTL_3 class I	0.133	0.177	0.11	0.166	0.088	0.154	ns
SSTL33D_II	Differential SSTL_3 class II	0.173	0.247	0.164	0.253	0.156	0.258	ns
SSTL25_I	SSTL_2 class I	0.215	0.125	0.239	0.228	0.264	0.331	ns
SSTL25_II	SSTL_2 class II	0.277	0.181	0.311	0.284	0.345	0.387	ns
SSTL25D_I	Differential SSTL_2 class I	0.215	0.125	0.239	0.228	0.264	0.331	ns
SSTL25D_II	Differential SSTL_2 class II	0.277	0.181	0.311	0.284	0.345	0.387	ns
SSTL18_I	SSTL_2 class I	0.16	0.081	0.179	0.173	0.199	0.265	ns
SSTL18_II	SSTL_2 class II	0.238	0.15	0.263	0.244	0.295	0.338	ns
SSTL18D_I	Differential SSTL_2 class I	0.16	0.081	0.179	0.173	0.199	0.265	ns
SSTL18D_II	Differential SSTL_2 class II	0.238	0.15	0.263	0.244	0.295	0.338	ns
LVTTL33_8mA	LVTTL 8mA drive	-0.346	-0.165	-0.496	-0.296	-0.646	-0.428	ns
LVTTL33_16mA	LVTTL 16mA drive	-0.11	-0.18	-0.218	-0.32	-0.325	-0.46	ns
LVTTL33_24mA	LVTTL 24mA drive	-0.012	-0.18	-0.099	-0.321	-0.185	-0.463	ns
LVCMOS33_8mA	LVCMOS 3.3 8mA drive	-0.346	-0.165	-0.496	-0.296	-0.646	-0.428	ns
LVCMOS33_16mA	LVCMOS 3.3 16mA drive	-0.11	-0.18	-0.218	-0.32	-0.325	-0.46	ns
LVCMOS33_24mA	LVCMOS 3.3 24mA drive	-0.012	-0.18	-0.099	-0.321	-0.185	-0.463	ns
LVCMOS25_4mA	LVCMOS 2.5 4mA drive	-0.174	0.004	-0.195	0.002	-0.215	0	ns
LVCMOS25_8mA	LVCMOS 2.5 8mA drive	0	0	0	0	0	0	ns
LVCMOS25_12mA	LVCMOS 2.5 12mA drive	0.094	-0.025	0.107	0.096	0.12	0.216	ns
LVCMOS25_16mA	LVCMOS 2.5 16mA drive	0.145	-0.054	0.162	0.063	0.181	0.179	ns
LVCMOS25_OD	LVCMOS 2.5 open drain	0.073	-0.125	0.081	-0.081	0.091	-0.09	ns
LVCMOS18_4mA	LVCMOS 1.8 4mA drive	-0.278	-0.099	-0.312	-0.115	-0.345	-0.131	ns
LVCMOS18_8mA	LVCMOS 1.8 8mA drive	-0.073	-0.078	-0.078	-0.084	-0.083	-0.089	ns

Figure 3-8. Read Mode with Input and Output Registers

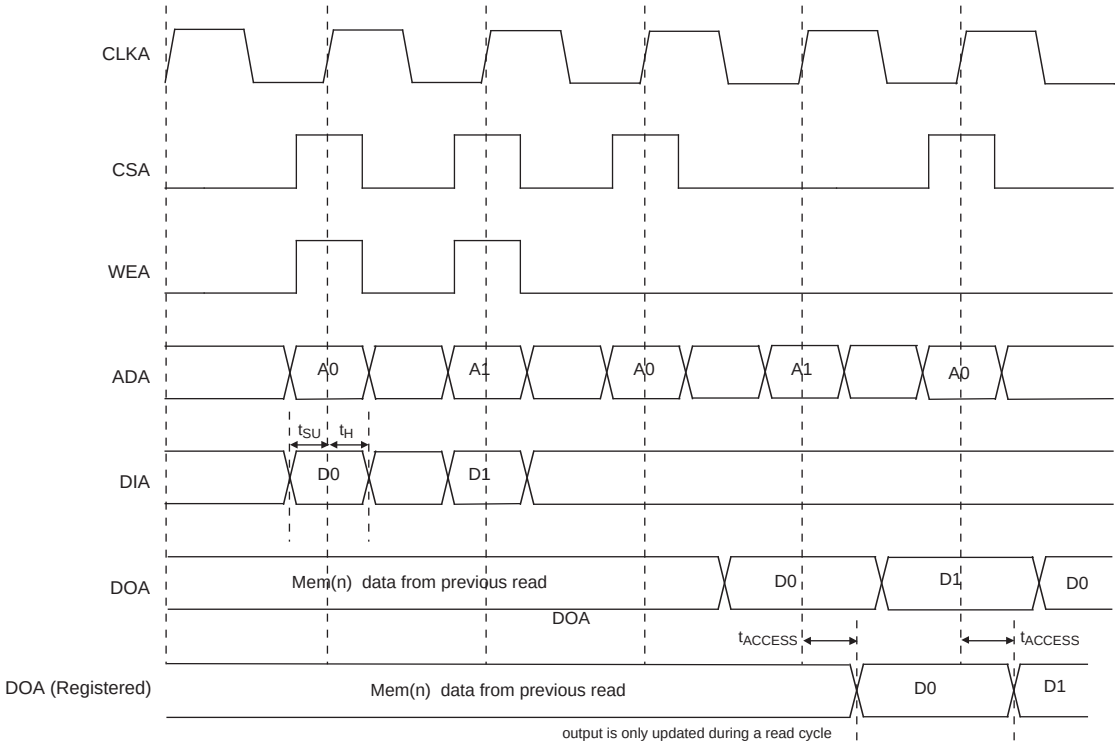
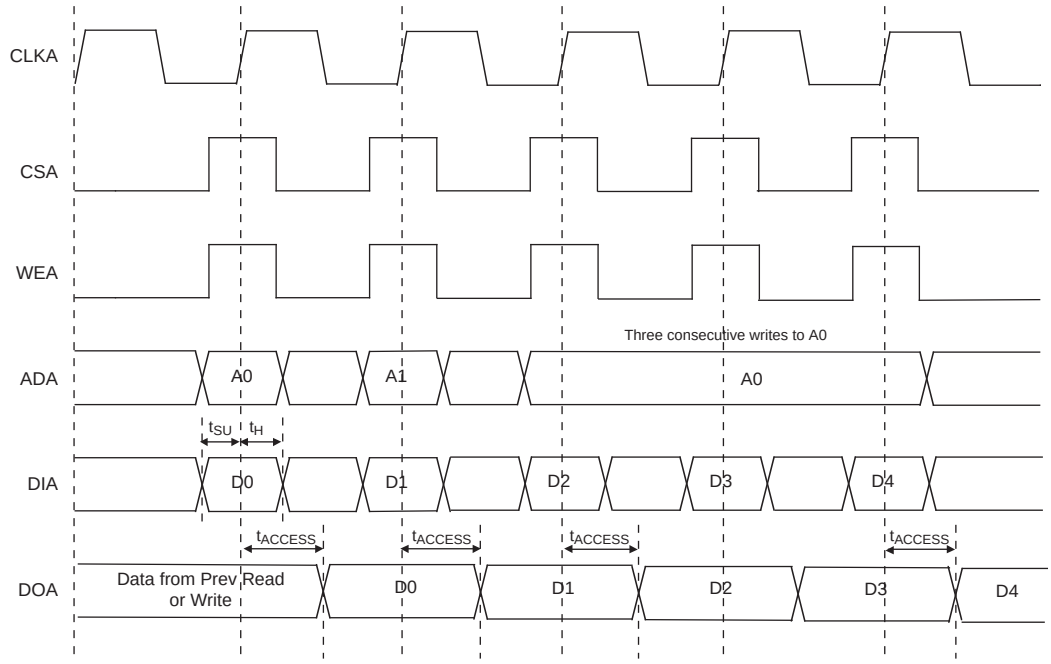


Figure 3-9. Write Through (SP Read/Write On Port A, Input Registers Only)



Note: Input data and address are registered at the positive edge of the clock and output data appears after the positive of the clock.

LatticeSC/M sysCONFIG Port Timing

Over Recommended Operating Conditions

Parameter	Description	Min.	Max.	Units
General Configuration Timing				
t_{SMODE}	M[3:0] Setup Time to INITN High	0	—	ns
t_{HMODE}	M[3:0] Hold Time from INITN High	600	—	ns
t_{RW}	RESETN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
t_{PGW}	PROGRAMN Pulse Width Low to Start Reconfiguration (1.2 V)	50 (or 100 at 0.95V)	—	ns
$f_{ESB\_CLK\_FRQ}$	System Bus ESB_CLK Frequency (No Wait States)	—	133	MHz
sysCONFIG Master Parallel Configuration Mode				
t_{SMB}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMB}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMB}	RCLK Low Time (Non-compressed Bitstreams)	0.5	0.5	CCLK periods
	RCLK Low Time (Compressed Bitstreams)	0.5	7.5	CCLK periods
t_{CHMB}	RCLK High Time	0.5	0.5	CCLK periods
sysCONFIG SPI Port				
t_{CFGX}	INITN High to CSCK Low	—	80	ns
t_{CSSPI}	INITN High to CSSPIN Low	0	2	µs
t_{SCK}	CSCK Low before CSSPIN Low	0	—	ns
t_{SOCDO}	CSCK Low to Output Valid	—	15	ns
t_{CSPID}	CSSPIN Low to CSCK high Setup Time	—	15	ns
f_{MAXSPI}	Max CCLK Frequency - SPI Flash Fast Read Opcode (0x0B) (SPIFASTN=0)	—	50	MHz
t_{SUSPI}	SOSPI/D0 Data Setup Time Before CSCK	7	—	ns
t_{HSPI}	SOSPI/D0 Data Hold Time After CSCK	2	—	ns
	Master Clock Frequency	Selected value - 30%	Selected value + 30%	MHz
	Duty Cycle	40	60	%
sysCONFIG Master Serial Configuration Mode				
t_{SMS}	DIN Setup Time	4.4	—	ns
t_{HMS}	DIN Hold Time	0	—	ns
f_{CMS}	CCLK Frequency (No Divider)	90	190	MHz
f_{C_DIV}	CCLK Frequency (Div 128)	0.70	1.48	MHz
t_{D}	CCLK to DOUT Delay	—	7.5	ns
sysCONFIG Master Parallel Configuration Mode				
t_{AVMP}	RCLK to Address Valid	—	10	ns
t_{SMP}	D[7:0] Setup Time to RCLK High	6	—	ns
t_{HMP}	D[7:0] Hold Time to RCLK High	0	—	ns
t_{CLMP}	RCLK Low Time (Non-compressed Bitstream)	7.5	7.5	CCLK periods
	RCLK Low Time (Compressed Bitstream)	0.5	63.5	
t_{CHMP}	RCLK High Time	0.5	0.5	CCLK periods
t_{DMP}	CCLK to DOUT	—	7.5	ns

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2]

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
E4	A_VDDAX25_L	-	
B1	A_REFCLKP_L	-	
C1	A_REFCLKN_L	-	
D2	RESP_ULC	-	
F5	RESETN	1	
D1	DONE	1	
E1	INITN	1	
E2	M0	1	
E3	M1	1	
E5	M2	1	
E6	M3	1	
F2	PL15A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
F1	PL15B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
F3	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
G1	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
G4	PL18D	7	VREF2_7
H3	PL22A	7	
H2	PL22B	7	
H5	PL22C	7	VREF1_7
G5	PL22D	7	DIFFR_7
H1	PL23A	7	PCLKT7_1
J1	PL23B	7	PCLKC7_1
J2	PL24A	7	PCLKT7_0
J3	PL24B	7	PCLKC7_0
H4	PL24C	7	PCLKT7_2
H6	PL24D	7	PCLKC7_2
J4	PL26A	6	PCLKT6_0
K5	PL26B	6	PCLKC6_0
J5	PL26C	6	PCLKT6_1
J6	PL26D	6	PCLKC6_1
K1	PL28A	6	
L1	PL28B	6	
L4	PL28C	6	PCLKT6_2
K4	PL28D	6	PCLKC6_2
L2	PL31C	6	VREF1_6
L3	PL35A	6	
M3	PL35B	6	
M2	PL35D	6	DIFFR_6
M1	PL37A	6	
N1	PL37B	6	
P2	PL41D	6	VREF2_6
M5	PL43A	6	

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2] (Cont.)

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
J9	VCC	-	
K8	VCC	-	
F6	VCC12	-	
F11	VCC12	-	
L11	VCC12	-	
L6	VCC12	-	
K7	VCC12	-	
K10	VCC12	-	
F10	VCCAUX	-	
F7	VCCAUX	-	
T1	GND	-	
G11	VCCAUX	-	
K11	VCCAUX	-	
L10	VCCAUX	-	
L9	VCCAUX	-	
L7	VCCAUX	-	
L8	VCCAUX	-	
T16	GND	-	
G6	VCCAUX	-	
K6	VCCAUX	-	
B13	VCCIO1	-	
D11	VCCIO1	-	
D14	VCCIO1	-	
F12	VCCIO2	-	
G15	VCCIO2	-	
K14	VCCIO3	-	
N15	VCCIO3	-	
M11	VCCIO4	-	
P13	VCCIO4	-	
R10	VCCIO4	-	
N6	VCCIO5	-	
P7	VCCIO5	-	
R4	VCCIO5	-	
K2	VCCIO6	-	
N3	VCCIO6	-	
F4	VCCIO7	-	
G3	VCCIO7	-	
D4	VCC12	-	
D7	VCC12	-	
D5	VCC12	-	
D6	VCC12	-	

1. Differential pair grouping within a PIC is A (True) and B (Complement) and C (True) and D (Complement).
2. The LatticeSC/M15 in a 256-pin package does not support an MPI interface.

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH29	PB48B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D	PB68B	4	LRC_DLLC_IN_C/LRC_DLLC_FB_D
AE26	PB48C	4		PB68C	4	
AD25	PB48D	4		PB68D	4	
AJ30	PB49A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B	PB69A	4	LRC_PLLT_IN_A/LRC_PLLT_FB_B
AH30	PB49B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B	PB69B	4	LRC_PLLC_IN_A/LRC_PLLC_FB_B
AG28	PB49C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C	PB69C	4	LRC_DLLT_IN_D/LRC_DLLT_FB_C
AG29	PB49D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C	PB69D	4	LRC_DLLC_IN_D/LRC_DLLC_FB_C
AF26	VCC12	-		VCC12	-	
AD27	PROBE_VCC	-		PROBE_VCC	-	
AG27	VCC12	-		VCC12	-	
AE28	PROBE_GND	-		PROBE_GND	-	
AC25	PR45D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A	PR57D	3	LRC_PLLC_IN_B/LRC_PLLC_FB_A
AD26	PR45C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A	PR57C	3	LRC_PLLT_IN_B/LRC_PLLT_FB_A
AF28	PR45B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E	PR57B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AF29	PR45A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E	PR57A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AC26	PR44D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F	PR55D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AB26	PR44C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F	PR55C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AG30	PR44B	3		PR55B	3	
AF30	PR44A	3		PR55A	3	
AC28	PR43B	3		PR52B	3	
AB28	PR43A	3		PR52A	3	
AB27	PR41D	3	VREF2_3	PR51D	3	VREF2_3
AE30	PR41B	3		PR51B	3	
AD30	PR41A	3		PR51A	3	
AB25	PR40B	3		PR49B	3	
AA25	PR40A	3		PR49A	3	
AA30	PR39B	3		PR48B	3	
Y30	PR39A	3		PR48A	3	
W29	PR37B	3		PR44B	3	
V29	PR37A	3		PR44A	3	
U30	PR36B	3		PR43B	3	
T30	PR36A	3		PR43A	3	
V25	PR35D	3	DIFFR_3	PR42D	3	DIFFR_3
W28	PR35B	3		PR42B	3	
V28	PR35A	3		PR42A	3	
R30	PR33B	3		PR38B	3	
P30	PR33A	3		PR38A	3	
N30	PR32B	3		PR35B	3	
M29	PR32A	3		PR35A	3	
U26	PR31D	3		PR34D	3	
T26	PR31C	3	VREF1_3	PR34C	3	VREF1_3
U28	PR31B	3		PR34B	3	
T28	PR31A	3		PR34A	3	
M30	PR28D	3	PCLKC3_2	PR31D	3	PCLKC3_2
L29	PR28C	3	PCLKT3_2	PR31C	3	PCLKT3_2

LFSC/M15, LFSC/M25 Logic Signal Connections: 900 fpBGA[1, 2] (Cont.)

Ball Number	LFSC/M15			LFSC/M25		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AB10	VCC	-		VCC	-	
AB21	VCC	-		VCC	-	
J10	VCC	-		VCC	-	
J21	VCC	-		VCC	-	
K10	VCC	-		VCC	-	
K11	VCC	-		VCC	-	
K12	VCC	-		VCC	-	
K13	VCC	-		VCC	-	
K14	VCC	-		VCC	-	
K17	VCC	-		VCC	-	
K18	VCC	-		VCC	-	
K19	VCC	-		VCC	-	
K20	VCC	-		VCC	-	
K21	VCC	-		VCC	-	
K22	VCC	-		VCC	-	
K9	VCC	-		VCC	-	
L10	VCC	-		VCC	-	
L21	VCC	-		VCC	-	
M10	VCC	-		VCC	-	
M21	VCC	-		VCC	-	
N10	VCC	-		VCC	-	
N21	VCC	-		VCC	-	
P10	VCC	-		VCC	-	
P21	VCC	-		VCC	-	
U10	VCC	-		VCC	-	
U21	VCC	-		VCC	-	
V10	VCC	-		VCC	-	
V21	VCC	-		VCC	-	
W10	VCC	-		VCC	-	
W21	VCC	-		VCC	-	
Y10	VCC	-		VCC	-	
Y21	VCC	-		VCC	-	
H11	VCCAUX	-		VCCAUX	-	
H12	VCCAUX	-		VCCAUX	-	
H19	VCCAUX	-		VCCAUX	-	
H20	VCCAUX	-		VCCAUX	-	
M23	VCCAUX	-		VCCAUX	-	
M24	VCCAUX	-		VCCAUX	-	
N23	VCCAUX	-		VCCAUX	-	
N24	VCCAUX	-		VCCAUX	-	
U23	VCCAUX	-		VCCAUX	-	
U24	VCCAUX	-		VCCAUX	-	
V23	VCCAUX	-		VCCAUX	-	
V24	VCCAUX	-		VCCAUX	-	
W23	VCCAUX	-		VCCAUX	-	

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
G6	A_HDINN2_R	-	PCS 3E0 CH 2 IN N	A_HDINN2_R	-	PCS 3E0 CH 2 IN N
A6	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P	A_HDOUTP2_R	-	PCS 3E0 CH 2 OUT P
D6	A_VDDOB2_R	-		A_VDDOB2_R	-	
B6	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N	A_HDOUTN2_R	-	PCS 3E0 CH 2 OUT N
D7	A_VDDOB3_R	-		A_VDDOB3_R	-	
B7	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N	A_HDOUTN3_R	-	PCS 3E0 CH 3 OUT N
A7	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P	A_HDOUTP3_R	-	PCS 3E0 CH 3 OUT P
G7	A_HDINN3_R	-	PCS 3E0 CH 3 IN N	A_HDINN3_R	-	PCS 3E0 CH 3 IN N
F7	A_HDINP3_R	-	PCS 3E0 CH 3 IN P	A_HDINP3_R	-	PCS 3E0 CH 3 IN P
H7	A_VDDIB3_R	-		A_VDDIB3_R	-	
H8	B_VDDIB0_R	-		B_VDDIB0_R	-	
F8	B_HDINP0_R	-	PCS 3E1 CH 0 IN P	B_HDINP0_R	-	PCS 3E1 CH 0 IN P
G8	B_HDINN0_R	-	PCS 3E1 CH 0 IN N	B_HDINN0_R	-	PCS 3E1 CH 0 IN N
A8	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P	B_HDOUTP0_R	-	PCS 3E1 CH 0 OUT P
D8	B_VDDOB0_R	-		B_VDDOB0_R	-	
B8	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N	B_HDOUTN0_R	-	PCS 3E1 CH 0 OUT N
D9	B_VDDOB1_R	-		B_VDDOB1_R	-	
B9	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N	B_HDOUTN1_R	-	PCS 3E1 CH 1 OUT N
A9	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P	B_HDOUTP1_R	-	PCS 3E1 CH 1 OUT P
H10	B_HDINN1_R	-	PCS 3E1 CH 1 IN N	B_HDINN1_R	-	PCS 3E1 CH 1 IN N
G10	B_HDINP1_R	-	PCS 3E1 CH 1 IN P	B_HDINP1_R	-	PCS 3E1 CH 1 IN P
H9	B_VDDIB1_R	-		B_VDDIB1_R	-	
H11	B_VDDIB2_R	-		B_VDDIB2_R	-	
F11	B_HDINP2_R	-	PCS 3E1 CH 2 IN P	B_HDINP2_R	-	PCS 3E1 CH 2 IN P
G11	B_HDINN2_R	-	PCS 3E1 CH 2 IN N	B_HDINN2_R	-	PCS 3E1 CH 2 IN N
A11	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P	B_HDOUTP2_R	-	PCS 3E1 CH 2 OUT P
D11	B_VDDOB2_R	-		B_VDDOB2_R	-	
B11	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N	B_HDOUTN2_R	-	PCS 3E1 CH 2 OUT N
D12	B_VDDOB3_R	-		B_VDDOB3_R	-	
B12	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N	B_HDOUTN3_R	-	PCS 3E1 CH 3 OUT N
A12	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P	B_HDOUTP3_R	-	PCS 3E1 CH 3 OUT P
G12	B_HDINN3_R	-	PCS 3E1 CH 3 IN N	B_HDINN3_R	-	PCS 3E1 CH 3 IN N
F12	B_HDINP3_R	-	PCS 3E1 CH 3 IN P	B_HDINP3_R	-	PCS 3E1 CH 3 IN P
H12	B_VDDIB3_R	-		B_VDDIB3_R	-	
B10	VCC12	-		VCC12	-	
D10	B_REFCLKN_R	-		B_REFCLKN_R	-	
C10	B_REFCLKP_R	-		B_REFCLKP_R	-	
J15	PT49D	1	HDC/SI	PT61D	1	HDC/SI
K15	PT49C	1	LDCN/SCS	PT61C	1	LDCN/SCS
E13	PT49B	1	D8/MPI_DATA8	PT59B	1	D8/MPI_DATA8
F13	PT49A	1	CS1/MPI_CS1	PT59A	1	CS1/MPI_CS1
H13	PT47D	1	D9/MPI_DATA9	PT58D	1	D9/MPI_DATA9
G13	PT47C	1	D10/MPI_DATA10	PT58C	1	D10/MPI_DATA10
E14	PT47B	1	CS0N/MPI_CS0N	PT57B	1	CS0N/MPI_CS0N
F14	PT47A	1	RDN/MPI_STRB_N	PT57A	1	RDN/MPI_STRB_N
H14	PT46D	1	WRN/MPI_WR_N	PT55D	1	WRN/MPI_WR_N
G14	PT46C	1	D7/MPI_DATA7	PT55C	1	D7/MPI_DATA7
D13	PT46B	1	D6/MPI_DATA6	PT55B	1	D6/MPI_DATA6
D14	PT46A	1	D5/MPI_DATA5	PT55A	1	D5/MPI_DATA5
E15	PT45D	1	D4/MPI_DATA4	PT54D	1	D4/MPI_DATA4

LFSC/M25, LFSC/M40 Logic Signal Connections: 1020 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M25			LFSC/M40		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
P17	VCC	-		VCC	-	
P19	VCC	-		VCC	-	
R13	VCC	-		VCC	-	
R15	VCC	-		VCC	-	
R18	VCC	-		VCC	-	
R20	VCC	-		VCC	-	
T13	VCC	-		VCC	-	
T14	VCC	-		VCC	-	
T16	VCC	-		VCC	-	
T17	VCC	-		VCC	-	
T19	VCC	-		VCC	-	
T20	VCC	-		VCC	-	
U13	VCC	-		VCC	-	
U14	VCC	-		VCC	-	
U16	VCC	-		VCC	-	
U17	VCC	-		VCC	-	
U19	VCC	-		VCC	-	
U20	VCC	-		VCC	-	
V13	VCC	-		VCC	-	
V15	VCC	-		VCC	-	
V18	VCC	-		VCC	-	
V20	VCC	-		VCC	-	
W14	VCC	-		VCC	-	
W16	VCC	-		VCC	-	
W17	VCC	-		VCC	-	
W19	VCC	-		VCC	-	
Y13	VCC	-		VCC	-	
Y15	VCC	-		VCC	-	
Y16	VCC	-		VCC	-	
Y17	VCC	-		VCC	-	
Y18	VCC	-		VCC	-	
Y20	VCC	-		VCC	-	
C17	VCCIO1	-		VCCIO1	-	
D16	VCCIO1	-		VCCIO1	-	
F15	VCCIO1	-		VCCIO1	-	
F24	VCCIO1	-		VCCIO1	-	
G18	VCCIO1	-		VCCIO1	-	
G9	VCCIO1	-		VCCIO1	-	
J11	VCCIO1	-		VCCIO1	-	
J19	VCCIO1	-		VCCIO1	-	
K14	VCCIO1	-		VCCIO1	-	
K22	VCCIO1	-		VCCIO1	-	
G4	VCCIO2	-		VCCIO2	-	
J7	VCCIO2	-		VCCIO2	-	
K3	VCCIO2	-		VCCIO2	-	
L10	VCCIO2	-		VCCIO2	-	
M6	VCCIO2	-		VCCIO2	-	
N4	VCCIO2	-		VCCIO2	-	
P9	VCCIO2	-		VCCIO2	-	
R7	VCCIO2	-		VCCIO2	-	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
H21	PT38D	1	D28/PCLKC1_6/MPI_DATA28	PT57D	1	D28/PCLKC1_6/MPI_DATA28
J21	PT38C	1	D29/PCLKT1_6/MPI_DATA29	PT57C	1	D29/PCLKT1_6/MPI_DATA29
A19	PT38B	1	A9/MPI_ADDR23	PT57B	1	A9/MPI_ADDR23
B19	PT38A	1	A10/MPI_ADDR24	PT57A	1	A10/MPI_ADDR24
H22	PT37D	1	D30/PCLKC1_7/MPI_DATA30	PT56D	1	D30/PCLKC1_7/MPI_DATA30
J22	PT37C	1	D31/PCLKT1_7/MPI_DATA31	PT56C	1	D31/PCLKT1_7/MPI_DATA31
F20	PT37B	1	A11/MPI_ADDR25	PT56B	1	A11/MPI_ADDR25
G20	PT37A	1	A12/MPI_ADDR26	PT56A	1	A12/MPI_ADDR26
K21	PT35D	1	D11/MPI_DATA11	PT55D	1	D11/MPI_DATA11
K22	PT35C	1	D12/MPI_DATA12	PT55C	1	D12/MPI_DATA12
A20	PT35B	1	A13/MPI_ADDR27	PT55B	1	A13/MPI_ADDR27
B20	PT35A	1	A14/MPI_ADDR28	PT55A	1	A14/MPI_ADDR28
L21	PT33D	1	A16/MPI_ADDR30	PT53D	1	A16/MPI_ADDR30
L20	PT33C	1	D13/MPI_DATA13	PT53C	1	D13/MPI_DATA13
D20	PT33B	1	A15/MPI_ADDR29	PT53B	1	A15/MPI_ADDR29
E20	PT33A	1	A17/MPI_ADDR31	PT53A	1	A17/MPI_ADDR31
L19	PT30D	1	A19/MPI_TSIZ1	PT52D	1	A19/MPI_TSIZ1
K19	PT30C	1	A20/MPI_BDIP	PT52C	1	A20/MPI_BDIP
D21	PT30B	1	A18/MPI_TSIZ0	PT52B	1	A18/MPI_TSIZ0
E21	PT30A	1	MPI_TEA	PT52A	1	MPI_TEA
M20	PT28D	1	D14/MPI_DATA14	PT51D	1	D14/MPI_DATA14
M19	PT28C	1	DP1/MPI_PAR1	PT51C	1	DP1/MPI_PAR1
F21	PT27B	1	A21/MPI_BURST	PT51B	1	A21/MPI_BURST
G21	PT27A	1	D15/MPI_DATA15	PT51A	1	D15/MPI_DATA15
H24	B_REFCLKP_L	-		B_REFCLKP_L	-	
J24	B_REFCLKN_L	-		B_REFCLKN_L	-	
L22	VCC12	-		VCC12	-	
E26	B_VDDIB3_L	-		B_VDDIB3_L	-	
G22	VCC12	-		VCC12	-	
E22	B_HDINP3_L	-	PCS 361 CH 3 IN P	B_HDINP3_L	-	PCS 361 CH 3 IN P
F22	B_HDINN3_L	-	PCS 361 CH 3 IN N	B_HDINN3_L	-	PCS 361 CH 3 IN N
A21	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P	B_HDOUTP3_L	-	PCS 361 CH 3 OUT P
L24	VCC12	-		VCC12	-	
B21	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N	B_HDOUTN3_L	-	PCS 361 CH 3 OUT N
D22	B_VDDOB3_L	-		B_VDDOB3_L	-	
B22	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N	B_HDOUTN2_L	-	PCS 361 CH 2 OUT N
D23	B_VDDOB2_L	-		B_VDDOB2_L	-	
A22	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P	B_HDOUTP2_L	-	PCS 361 CH 2 OUT P
K24	VCC12	-		VCC12	-	
F23	B_HDINN2_L	-	PCS 361 CH 2 IN N	B_HDINN2_L	-	PCS 361 CH 2 IN N
E23	B_HDINP2_L	-	PCS 361 CH 2 IN P	B_HDINP2_L	-	PCS 361 CH 2 IN P
D26	B_VDDIB2_L	-		B_VDDIB2_L	-	
G23	VCC12	-		VCC12	-	
D27	B_VDDIB1_L	-		B_VDDIB1_L	-	
G24	VCC12	-		VCC12	-	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
W30	PL69B	6	
W27	PL69C	6	VREF1_6
Y27	PL69D	6	
T33	PL70A	6	
U33	PL70B	6	
V25	PL70C	6	
W25	PL70D	6	
U34	PL71A	6	
V34	PL71B	6	
V26	PL71C	6	
W26	PL71D	6	
V33	PL74A	6	
W33	PL74B	6	
V24	PL74C	6	
W24	PL74D	6	
W31	PL77A	6	
Y31	PL77B	6	
Y29	PL77C	6	
AA29	PL77D	6	
Y33	PL79A	6	
AA33	PL79B	6	
Y28	PL79C	6	
AA28	PL79D	6	
AB32	PL90A	6	
AC32	PL90B	6	
AA26	PL90C	6	
AA27	PL90D	6	DIFFR_6
AB31	PL91A	6	
AC31	PL91B	6	
Y24	PL91C	6	
AA24	PL91D	6	
AE34	PL92A	6	
AF34	PL92B	6	
AB30	PL92C	6	
AC30	PL92D	6	
AD33	PL94A	6	
AE33	PL94B	6	
AD30	PL94C	6	
AE30	PL94D	6	
AE32	PL96A	6	
AF32	PL96B	6	
AA25	PL96C	6	
AB25	PL96D	6	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AG38	NC	-		PL95A	6	
AH38	NC	-		PL95B	6	
AJ39	NC	-		PL100A	6	
AK39	NC	-		PL100B	6	
AL41	NC	-		PL105A	6	
AM41	NC	-		PL105B	6	
AN40	NC	-		PL108A	6	
AM40	NC	-		PL108B	6	
AM39	NC	-		PL111A	6	
AN39	NC	-		PL111B	6	
AR42	NC	-		PL113A	6	
AT42	NC	-		PL113B	6	
AT1	NC	-		PR113B	3	
AR1	NC	-		PR113A	3	
AN4	NC	-		PR111B	3	
AM4	NC	-		PR111A	3	
AM3	NC	-		PR108B	3	
AN3	NC	-		PR108A	3	
AM2	NC	-		PR105B	3	
AL2	NC	-		PR105A	3	
AK4	NC	-		PR100B	3	
AJ4	NC	-		PR100A	3	
AH5	NC	-		PR95B	3	
AG5	NC	-		PR95A	3	
P6	NC	-		PR39B	2	
N6	NC	-		PR39A	2	
L3	NC	-		PR36B	2	
K3	NC	-		PR36A	2	
M5	NC	-		PR35A	2	
L4	NC	-		PR32B	2	
K4	NC	-		PR32A	2	
A2	GND	-		GND	-	
A41	GND	-		GND	-	
AA20	GND	-		GND	-	
AA23	GND	-		GND	-	
AA3	GND	-		GND	-	
AA39	GND	-		GND	-	
AB20	GND	-		GND	-	
AB23	GND	-		GND	-	
AB4	GND	-		GND	-	
AB40	GND	-		GND	-	
AC17	GND	-		GND	-	
AC19	GND	-		GND	-	
AC21	GND	-		GND	-	
AC22	GND	-		GND	-	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSC3GA40E-7FFN1020C[1]	-7	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-6FFN1020C[1]	-6	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-5FFN1020C[1]	-5	Lead-Free Organic fcBGA	1020	COM	40.4
LFSC3GA40E-7FFAN1020C	-7	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-6FFAN1020C	-6	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-5FFAN1020C	-5	Lead-Free Organic fcBGA Revision 2	1020	COM	40.4
LFSC3GA40E-7FCN1152C[2]	-7	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-6FCN1152C[2]	-6	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-5FCN1152C[2]	-5	Lead-Free Ceramic fcBGA	1152	COM	40.4
LFSC3GA40E-7FFN1152C	-7	Lead-Free Organic fcBGA	1152	COM	40.4
LFSC3GA40E-6FFN1152C	-6	Lead-Free Organic fcBGA	1152	COM	40.4
LFSC3GA40E-5FFN1152C	-5	Lead-Free Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA40EP1-7FFN1020C[1]	-7	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-6FFN1020C[1]	-6	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-5FFN1020C[1]	-5	Organic fcBGA	1020	COM	40.4
LFSCM3GA40EP1-7FFAN1020C	-7	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-6FFAN1020C	-6	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-5FFAN1020C	-5	Organic fcBGA Revision 2	1020	COM	40.4
LFSCM3GA40EP1-7FCN1152C[2]	-7	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FCN1152C[2]	-6	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FCN1152C[2]	-5	Ceramic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-7FFN1152C	-7	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-6FFN1152C	-6	Organic fcBGA	1152	COM	40.4
LFSCM3GA40EP1-5FFN1152C	-5	Organic fcBGA	1152	COM	40.4

1. Converted to organic flip-chip BGA package revision 2 per PCN #02A-10.
2. Converted to organic flip-chip BGA package per PCN #01A-10.

Date	Version	Section	Change Summary
June 2006 (cont.)	01.2 (cont.)	DC and Switching Characteristics (cont.)	Updated Typical Building Block Performance with ispLEVER 6.0 values.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.0 values.
			Updated Lattice SC Internal Timing Parameters with ispLEVER 6.0 values.
			Updated Lattice SC Family Timing Adders with ispLEVER 6.0 values
			Changed % spread from 1 to 0.5 min and from 3 to 1.5 max.
			Changed conditions to refer to “with multiplication” and “without multiplication”.
			Changed the formula for t_{OPJIT} with multiplication (same result, different representation).
		Pinout Information	Expanded definition of NC.
			Expanded definition of GND.
			Expanded definition of VTT_x.
			Expanded definition of VCC12.
			Added accuracy of TEMP pin.
			Added RESPN_[ULC/URC].
			Updated Pin Information Summary with additional devices and packages.
			Added additional devices and packages pinouts.
			Removed Power Supply and NC connections table
			Removed VTT table
			Removed LFSC25 Logic Signal Connections: 900-Ball ffBGA1 table
			Changed all VDDP, VDDTX and VDDRX to VCC12.
		Ordering Information	Added dual marking.
			Added lead free packaging information to part number description.
August 2006	01.3	Introduction	Added SC40 1152 information to Table 1-1.
			Updated Table 1-3 with ispLEVER 6.0 SP1 results.
		Architecture	Added SSTL18 II to Table 2-8.
			Changed Table 2-10 VCCIO column to “N/A” for LVDS, mini-LVDS, BLVDS25, MLVDS25, HYPT and RSDS.
			Changed Hypertransport performance to 700 MHz (1400 Mbps) in Table 2-11.
			Changed SPI4.2 performance to 500 MHz (1000 Mbps) in Table 2-11
			Added “On packages that include PROBE_GND, the most accurate measurements will occur between the TEMP pin and the PROBE_GND pin. On packages that do not include PROBE_GND, measurements should be made between the TEMP pin and board ground.”
			Added VCCIO of 2.5 V for LVPECL33 in table 2-9.
		DC and Switching Characteristics	Updated Typical Building Block Performance with ispLEVER 6.0 SP1 results.
			Updated Initialization and Standby Supply Current table to break out ICC and ICC12.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.0 SP1 results.
			Updated LatticeSC Internal Timing Parameters with ispLEVER 6.0 SP1 results.

Date	Version	Section	Change Summary
September 2007	01.7	Pinout Information	Added Thermal Management text section.
		Supplemental Information	Updated title list.
November 2007	01.8	Ordering Information	Removed -7 speed grade information for 115K LUT devices in the Ordering Information tables.
January 2008	01.9	Introduction	Corrections/Additions to memory controller list (Tables 1-2).
		Architecture	AIL Overview – Modified power used by AIL block.
			PURESPEED I/O Buffer Banks – Modified VTT termination info. Added info about complimentary drivers for all banks.
			Supported Source Synchronous Interfaces – Modified data for DDRII in Table 2-11.
		DC and Switching Characteristics	Recommended Operating Conditions – Changed footnote 3.
			Initialization and Standby Supply Current – Inserted a paragraph with info regarding the table. Also updated the table.
			Typical Building Block Function Performance – Added VCC=1.2V=1.2V+/-5% above Pin to Pin Performance table.
			LatticeSC External Switching Characteristics – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 3.
			LatticeSC Family Timing Adders – Added VCC=1.2V=1.2V+/-5% above table.
			LatticeSC Internal Timing Parameters – Added VCC=1.2V=1.2V+/-5% above table. Reworded footnote 1.
			GSR Timing – Added a new table for Internal System Bus Timing after GSR Timing.
			LatticeSC sysCONFIG Port Timing – Corrected sysCONFIG SPI Port information.
		Pinout Information	Signal Descriptions – Modified info for VTT_x, PROBE_VCC, and PROBE_GND. Modified info for [LOC]_DLL[T,C]_IN[C,D,E,F].
		Supplemental Information	Updated list of technical notes, added reference to LatticeSC/M flexiPCS Data Sheet.
March 2008	02.0	DC and Switching Characteristics	Updated Internal Timing Parameters table.
			Updated Read Mode timing diagram.
			Updated Read Mode with Input Registers Only timing diagram.
June 2008	02.1	—	Data sheet status changed from preliminary to final.
		Architecture	Removed Read-Before-Write sysMEM EBR mode.
		DC and Switching Characteristics	Updated LatticeSC/M External Switching Characteristics table.
			Updated LatticeSC/M Internal Timing Parameters table.
			Removed Read-Before-Write sysMEM EBR mode.
December 2008	02.2	Architecture	Output/Tristate DDR/Shift Register Block Diagram - corrected connection to POS.
		DC and Switching Characteristics	DC and Switching Characteristics table - updated data for $t_{SUI\_PIO.}$
			Added $T_{R,}$ T_F parameter to PURESPEED I/O Differential Electrical Characteristics (LVDS) table.
		Multiple	Removed references to HyperTransport throughout the data sheet.
January 2010	02.3	Introduction	Updated per PCN #01A-10 (ceramic fcBGA conversion to organic fcBGA for the 1152-ball and 1704-ball fcBGA packages) and PCN #02A-10 (1020-ball organic fcBGA conversion to 1020-ball organic fcBGA revision 2 package).
		Ordering Information	